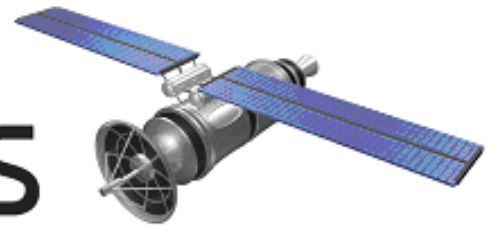


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The Global Semiconductor Industry Analysts

FH MONDAY

28 December 2020

Mentor Finally Becomes Siemens EDA From January 2021

In the world of mergers and acquisitions, one of the biggest challenges is how to present the combined company (or companies) to the outside world. When Siemens acquired Mentor Graphics for \$4.5 billion back in 2016, I am sure I am not the only member of the media who found the "Mentor, a Siemens business" rather clunky to use when writing articles.

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Micron Leapfrogs to 176-Layer 3D NAND Flash Memory

TORONTO — Micron Technology touted its use of replacement gate (RG) technology for its latest 3D NAND flash memory, which it said is the first 176-layer NAND shipping in volume, while other players are focused on 128-layer NAND.

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CEA-Leti to Collaborate with Intel on 3D Packaging Technologies

CEA-Leti has announced a new collaboration with Intel on 3D packaging technologies for processors to advance chip design. The research will focus on assembly of smaller chiplets, optimizing interconnection technologies between the different elements of microprocessors, and on new bonding and stacking technologies for 3D ICs, especially for making high performance computing (HPC) applications.

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TALK TO US



Fastweb Selects Qualcomm for 5G Fixed Wireless Access Commercial Launch in Italy

Fastweb announced today that its 5G millimeter wave (mmWave) Fixed Wireless Access (FWA) Customer Premise Equipment (CPE) devices will use the Snapdragon X55 Modem-RF System – building on the years-long collaboration between Fastweb and Qualcomm Technologies, Inc. to bring the world-leading performance and capacity of 5G mmWave to users in Italy.

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Eta Compute Pivots Away From Silicon, Signs Deal with Synaptics

AI chip startup Eta Compute has pivoted away from silicon to become a system solutions company specializing in AI at ultra-low power in edge devices and will exclusively license the company's Tensai Flow software..

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Well now, Siemens has announced, through a blog from Joe Sawicki, its executive vice president for IC-EDA, that the Mentor division will finally become Siemens EDA. The organization will continue to operate as part of Siemens Digital Industries Software.

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TORONTO — Micron Technology touted its use of replacement gate (RG) technology for its latest 3D NAND flash memory, which it said is the first 176-layer NAND shipping in volume, while other players are focused on 128-layer NAND.

Eschewing floating gate in favor of a charge trap approach and combining it with its CMOS-under-array architecture enables Micron to significantly improve performance and density, said Derek Dicker, corporate vice president and general manager of Micron’s storage business unit. The company’s 176-layer NAND improves both read latency and write latency by more than 35% compared with the company’s previous generation of high-volume 3D NAND and a layer count that is nearly 40% higher than its nearest competitor.

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3D technology, which stacks chips vertically in a device, not only optimizes the power of the chip with advanced packaging interconnects between components, but it also allows the creation of heterogeneous integration of chiplets. That ultimately allows fabrication of more efficient, thinner and lighter microprocessors. In addition, by implementing multiple heterogeneous solutions in a single package, chip companies benefit from considerable flexibility, such as mixing and matching different technology blocks with different IP and integrating memory and input / output technologies within the same component. This enables chip makers to continue to innovate and adapt to the needs of their customers and partners.

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Fastweb is the one of the first operators in Europe to launch commercial 5G Fixed Wireless Access connections using a 5G mmWave network. Taking advantage of the flexibility of 5G Fixed Wireless Access technology combined with the performance, capacity and cost-effectiveness of 5G mmWave, Fastweb will provide broadband connections to 12 million homes (i.e 45% of the population of Italy) with speeds of up to 1 Gbps within 2024 with the aim to close the digital divide in disadvantaged areas of the country.

Eta Compute Pivots Away From Silicon, Signs Deal with Synaptics

AI chip startup Eta Compute has pivoted away from silicon to become a system solutions company specializing in AI at ultra-low power in edge devices. The startup has also announced a strategic partnership with Synaptics, wherein Synaptics has invested in Eta Compute and will exclusively license the company’s Tensai Flow software. Moving forward, Eta Compute will continue to sell its existing ECM3532 ultra-low power AI chip, though there will be no further generations of Eta Compute silicon. The company will also develop boards and modules based on both the ECM3532 and Synaptics’ new Katana AI SoC.

Eta Compute also announced it has closed a series C round of funding, raising \$12.5 million, bringing the total funds raised to \$31.5 million. The round was led by Synaptics, along with participation from existing investors. Synaptics’ chief strategy officer, Satish Ganesan has joined the Eta Compute board of directors.